

Features

- Ultra low capacitance: 0.35pF typical
- Ultra low leakage: nA level
- Low operating voltage: 5V
- Low clamping voltage
- 2-pin leadless package
- Complies with following standards:
 - – IEC 61000-4-2 (ESD) immunity test
 - Air discharge: ±20kV
 - Contact discharge: ±15kV
 - – IEC61000-4-5 (Lightning)4A (8/20 μs)
- RoHS Compliant
- Lead Finish: NiPdAu

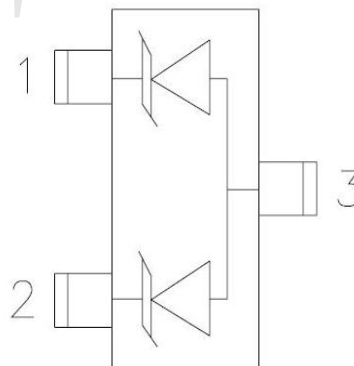
Mechanical Characteristics

- Package: SOT23
- Lead Finish: Matte Tin
- Case Material: “Green” Molding Compound.
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram Below
- Shipping Qty : 3000pcs/7Inch Tape & Reel

Applications

- USB 2.0 and USB 3.0
- SATA and eSATA
- DVI
- Set Top Box
- Portable Electronics

Dimensions and Pin Configuration



Absolute Maximum Ratings (Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20μs)	Ppk	100	W
Peak Pulse Current (8/20μs)	IPP	4	A
ESD per IEC 61000-4-2 (Air)	VESD	± 20	kV
ESD per IEC 61000-4-2 (Contact)		± 15	
Operating Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	Tstg	-55 to +150	°C

Electrical Characteristics (TA=25°C unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	VRWM			5	V	
Breakdown Voltage	VBR	6			V	IT = 1mA
Reverse Leakage Current	IR			0.08	μA	VRWM = 5V
Forward Voltage	VF		0.8	1.2	V	IF = 10mA
Clamping Voltage	VC			15	V	IPP = 1A (8 x 20μs pulse)
Clamping Voltage	VC			23	V	IPP = 4A (8 x 20μs pulse)
Junction Capacitance	CJ			0.7	pF	VR=0, f=1MHz, Pin 1 to Pin 3 or Pin 2 to Pin 3
Junction Capacitance	CJ		0.35		pF	VR=0, f=1MHz, Pin 1 to Pin 2

Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise Specified)

Fig1. 8/20 μs Pulse Waveform

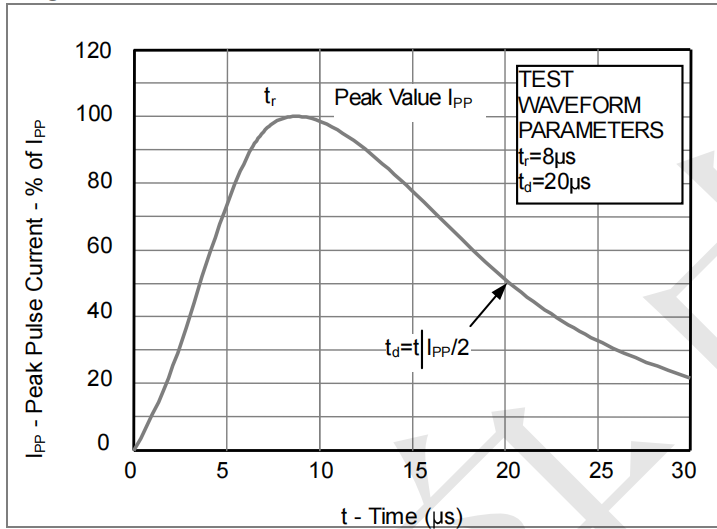


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

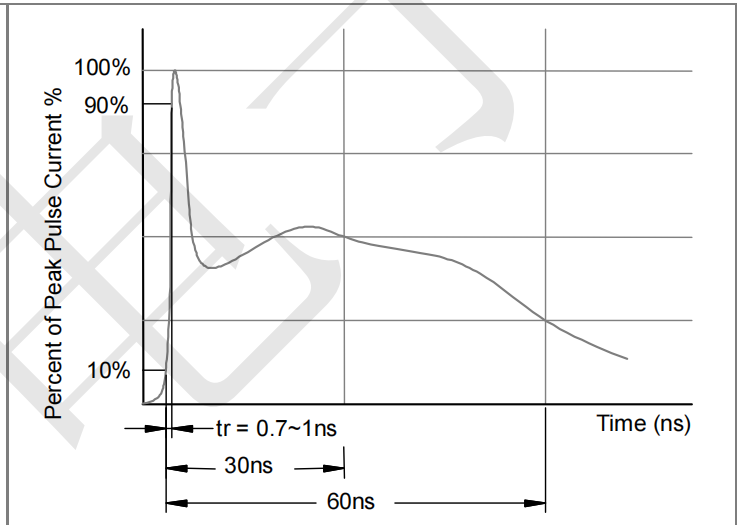
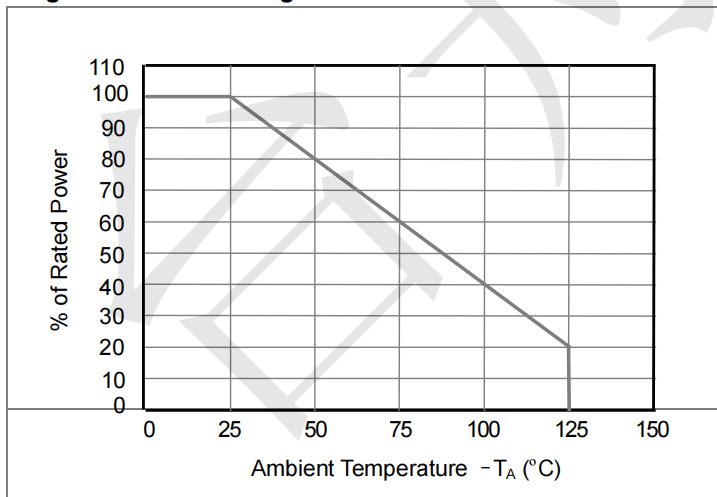
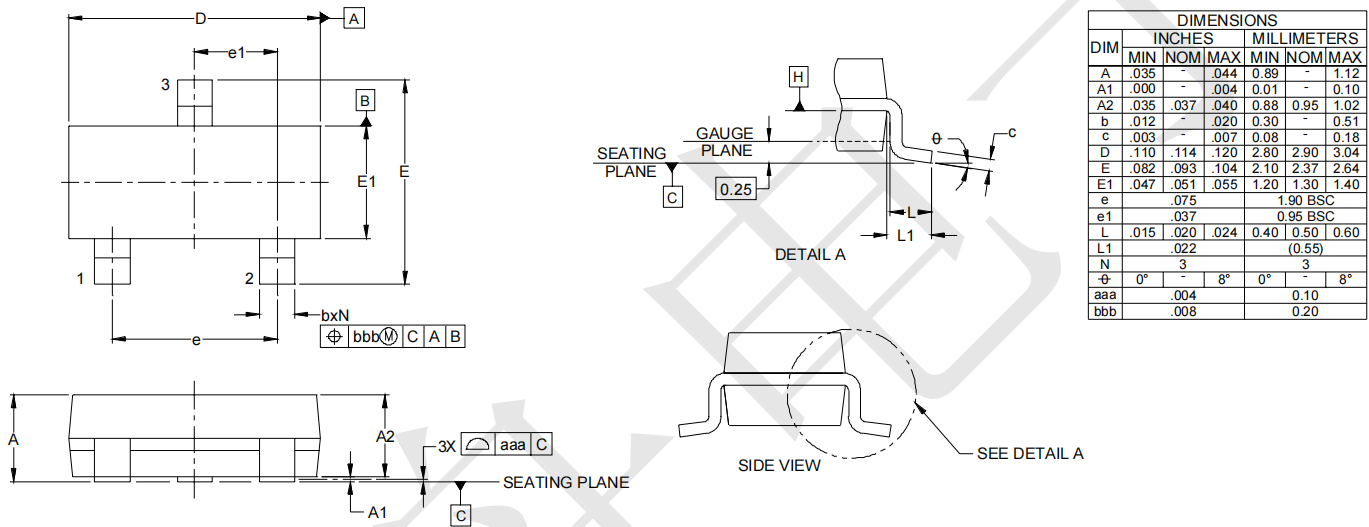


Fig3. Power Derating Curve



Outline Drawing - SOT23



Land Pattern - SOT23

